



DOCKET NO. CU-2417

EV548247510US

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

APPLICANT: Takahiro IJIMA et al) Group Art Unit: 2815
SERIAL NO: 09/736,864) Examiner: Chu, Chris C.
FILING DATE: December 14, 2000) Allowed: 04/02/2004
TITLE: INTERCONNECTION SUBSTRATE HAVING) Conf. No: 8303
METAL COLUMNS COVERED BY A RESIN FILM)
AND MANUFACTURING METHOD THEREOF)

MAIL STOP ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
Attention: Official Draftsman

SUBMISSION OF FORMAL DRAWINGS IN ALLOWED APPLICATION

Dear Sir:

This application was allowed on April 2, 2004.

Fresh formal drawings containing Figures 2A & 2B are submitted herewith (1 sheet) in order to meet the objections raised by the Examiner in the Notice of Allowability.

It is believed that the remaining sheets of drawings containing Figures 1A, 1B through 17 initially filed in this application are suitable as formal drawings.

Respectfully submitted,

Attorney for Applicant

July 1, 2004

Date

/4

Vangelis Economou, Reg. 32341
c/o Ladas & Parry
224 South Michigan Avenue
Chicago, Illinois 60604
(312) 427-1300